



SOT314-2

plastic low profile quad flat package; 64 leads; body 10 x 10 x 1.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	LQFP64
Package type industry code	LQFP64
Package style descriptive code	LQFP (low profile quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	136E10
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	25-2-2003

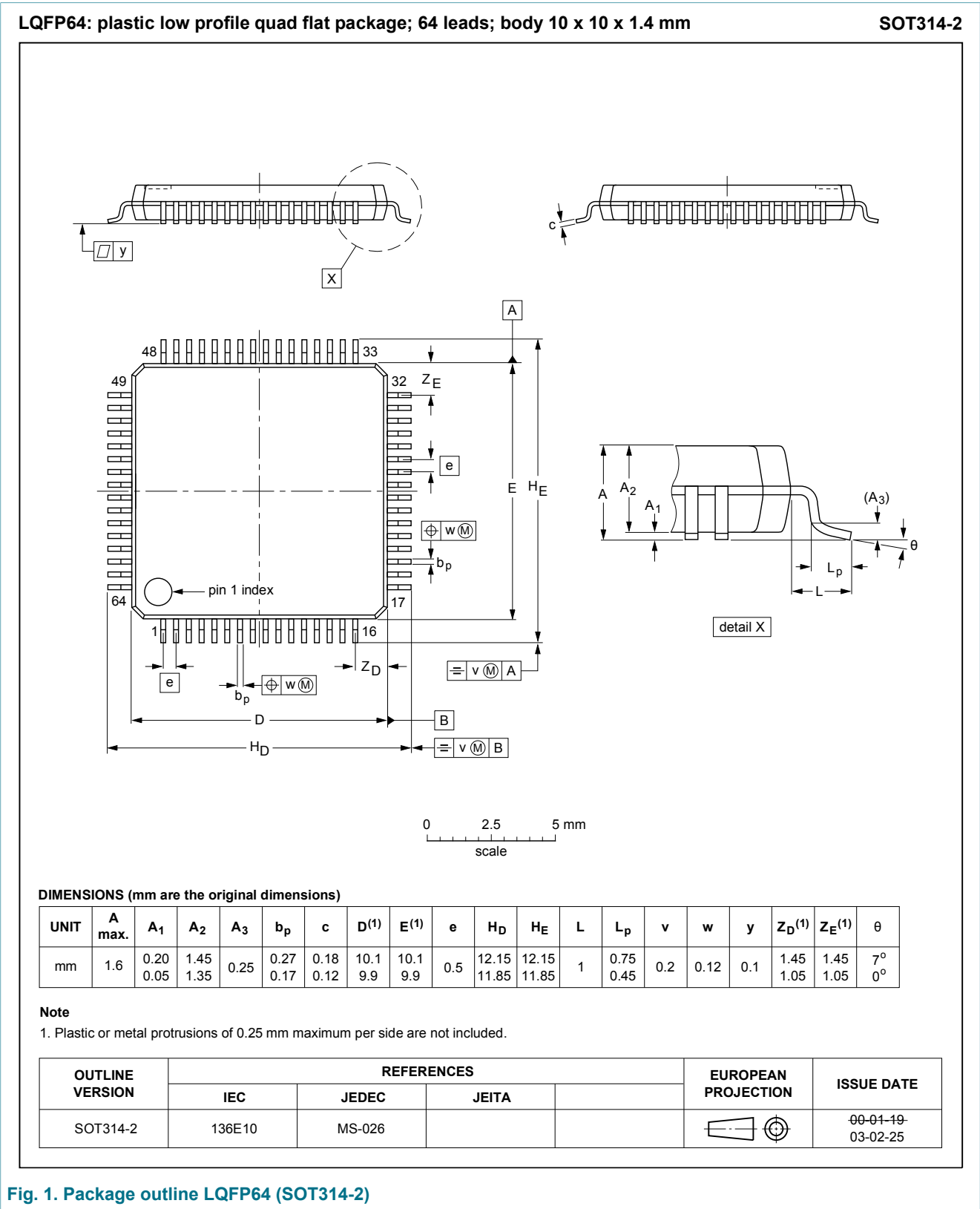
Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		9.9	-	10	10.1	mm
E	package width		9.9	-	10	10.1	mm
A	seated height		[tbd]	-	1.6	1.6	mm
A ₂	package height		1.35	-	1.4	1.45	mm
n ₂	actual quantity of termination		-	-	64	-	



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2. Package outline



3. Soldering

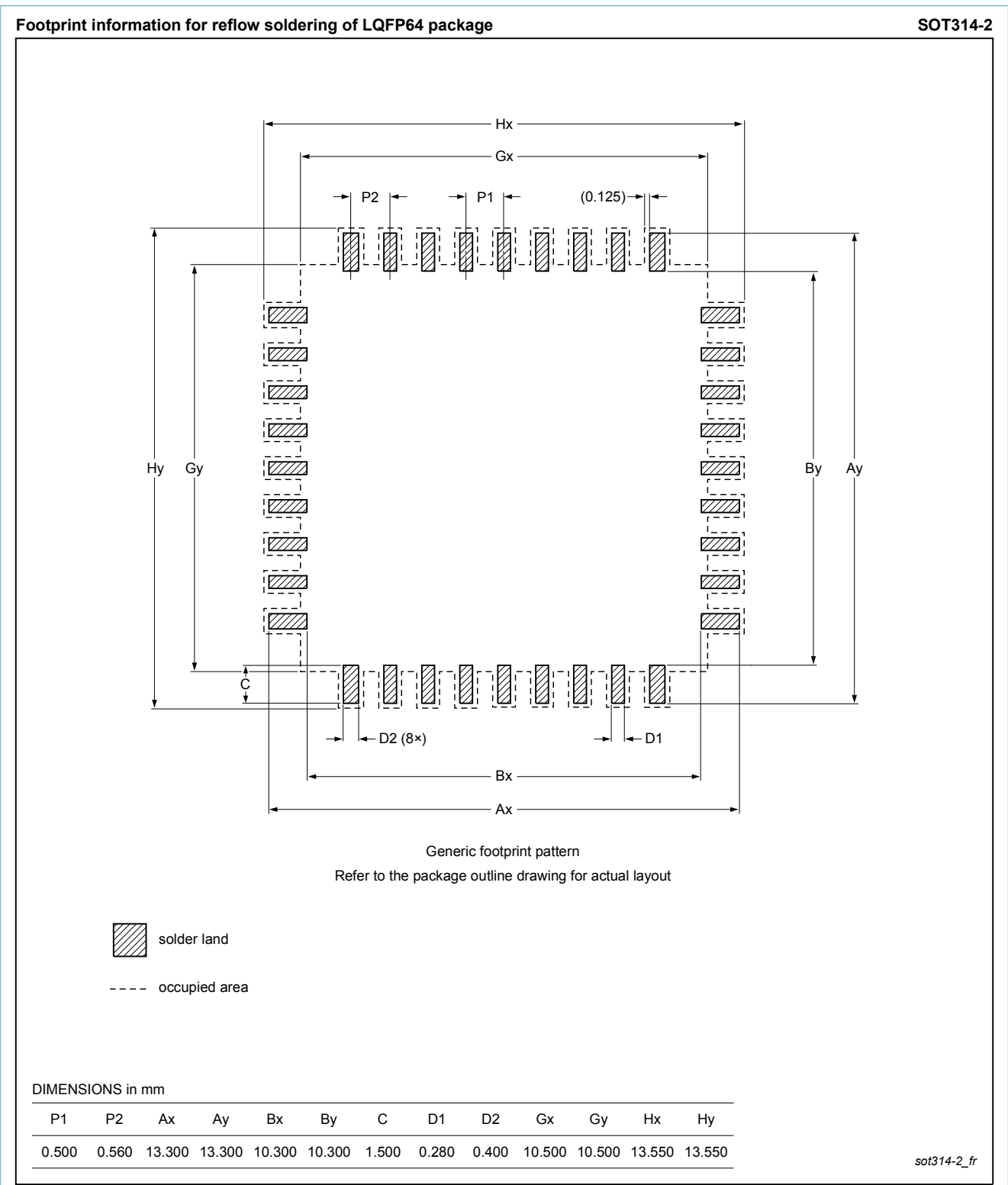


Fig. 2. Reflow soldering footprint for LQFP64 (SOT314-2)

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4. Legal information

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